

T6J06

ROW DRIVER FOR A DOT MATRIX LCD

The T6J06 is a 120-channel-output row driver for an STN dot matrix LCD. The T6J06 features an 80-V LCD drive voltage. The T6J06 is able to drive LCD panels with a duty ratio of up to 1/480. It is recommended for use with the T6C71.

Features

- Display duty application : to 1/480
- LCD drive signal : 120
- Data transfer : 120-bit bidirectional and 60-bit 2 division bidirectional
 - (1) O1 → O120
 - (2) O1 ← O120
 - (3) O1 → O60, O61 → O120
 - (4) O1 ← O60, O61 ← O120
- LCD drive voltage : $V_{CC} = 18.5$ to 42.5 V, $V_M = 2.5$ V, $V_{EE} = -13.5$ to -37.5 V
- Power supply voltage : 2.7 to 5.5 V
- Operating temperature : -20 to 75°C
- LCD drive output resistance: $0.6\text{ k}\Omega$ (typ.) ($V_{CC} = V_H = 32.5$ V, $V_{EE} = V_L = -27.5$ V)
- Display-off function : When/DSPOF is L, all LCD drive outputs (O1 to O120) remain at the V_M level.
- LCD drive output timing : Change on falling edge of LP
- Blanking function : Provision of a blanking interval prevents excessively high voltages being applied to the electrodes of the liquid crystal panel.
 /BLNK = L: Blanking. All LCD drive outputs (O1 to O120) are set to the V_M level.
 /BLNK = H: (O1 to O120) are operational.

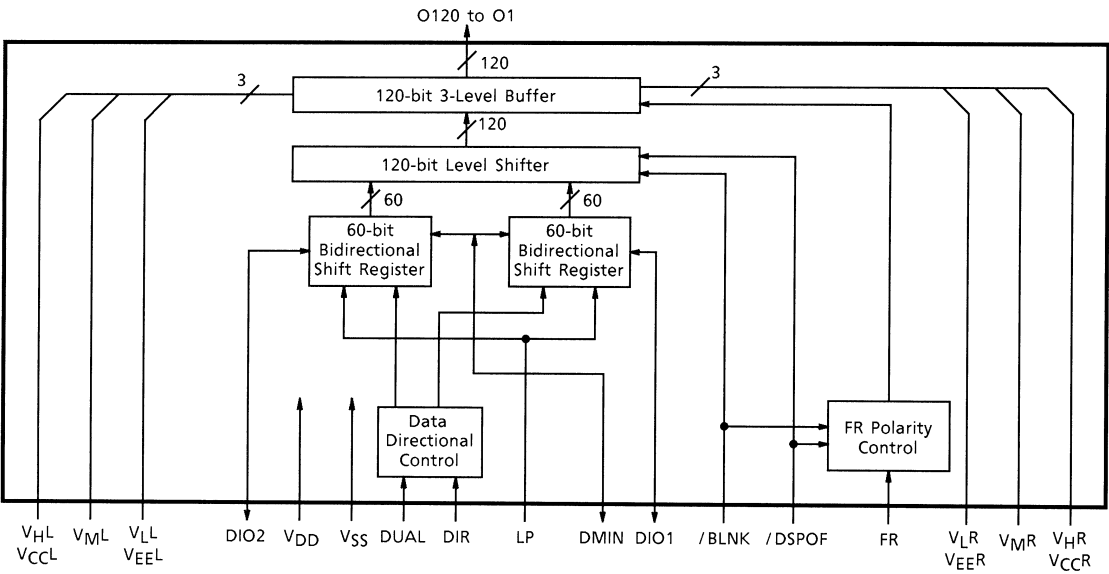
Unit: mm

T6J06	Lead Pitch	
	IN	OUT
(UFN, 3NS)	0.8	0.19
(UNM, 3NS)	0.8	0.26

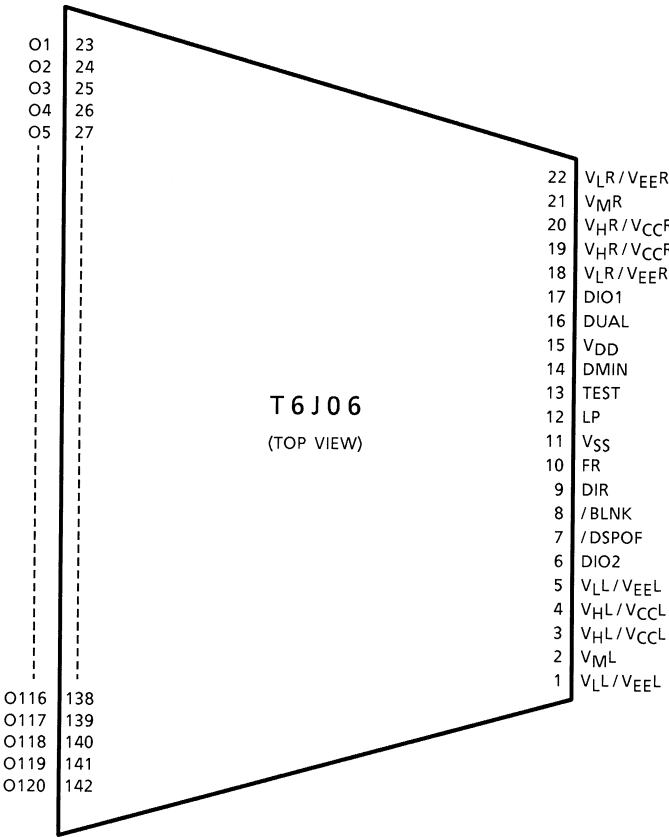
Please contact Toshiba or an authorized Toshiba dealer for information on package dimensions.

TCP (Tape Carrier Package)

Block Diagram



Pin Assignment



Note: The above diagram shows the pin configuration of the LSI chip, not that of the tape carrier package. It short-circuits V_{LL} and V_{EEEL}/V_{HL} and V_{CCCL} on the chip.

Pin Functions

Pin Name	I / O	Functions	Level
O1 to O120	Output	Output for LCD drive signal	$V_H / V_M / V_L$
DIO1, DIO2	I / O	Input / output for shift data DIR = L : DIO1 is input, DIO2 is output DIR = H : DIO1 is output, DIO2 is input	V_{DD} to V_{SS}
DMIN	Input	Dual Mode (DUAL = H) : data input Single Mode (DUAL = L) : open	
LP	Input	(Shift Clock Pulse) Input for shift clock pulse	
FR	Input	(Frame) Input for frame signal	
DUAL	Input	(Dual Mode) Terminal for dual input mode (H) or single input mode (L) select	
DIR	Input	(Direction) Input for data flow direction select	
/ DSPOF	Input	(Display Off) / DSPOF = L : Display-off mode, (O1 to O120) remain at the V_M level. Latch outputs cleared after release / DSPOF = H : Display-on mode, (O1 to O120) are operational	
/ BLNK	Input	(Blanking Function) Blanking-off mode. (O1 to O120) remain at V_M level. Latch outputs not cleared Blanking-on mode. (O1 to O120) are operational	
TEST	Input	(Test) Fix to L	—
V_{DD}	—	Power supply for internal logic (5 V)	
V_{SS}	—	Power supply for internal logic (0 V)	
V_{HL} / R V_{CCL} / R	—	Power supply for LCD drive circuit	
V_{ML} / R	—	Power supply for LCD drive circuit	
V_{LL} / R V_{EEL} / R	—	Power supply for LCD drive circuit	

Relation Between FR, Data Input and Output Level Format

F R	Data Input	/ Dspof or / Blnk	Output Level
L	L	H	V _M
L	H	H	V _H
H	L	H	V _M
H	H	H	V _L
Note	Note	L	V _M

Note: Don't Care

Data Input Format

Dual	DIR	Data Flow	Data Input Terminals		
			DIO 1	DIO 2	DMIN
L	L	O1 → O120	IN	OUT	OPEN
L	H	O120 → O1	OUT	IN	OPEN
H	L	O1 → O60	IN	—	—
		O61 → O120	—	OUT	IN
H	H	O60 → O1	OUT	—	IN
		O120 → O61	—	IN	—

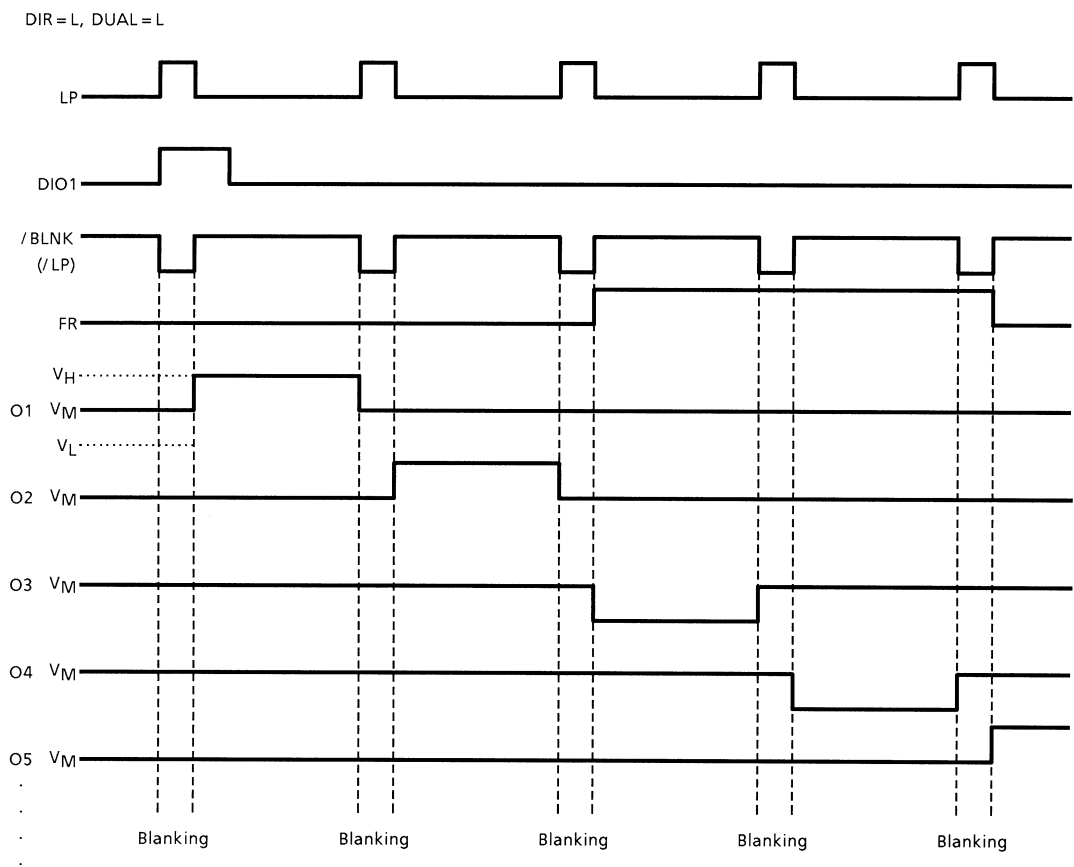
DIR=L, DUAL=L

Timing diagram showing signals over time. The time axis is marked with addresses: 480, 119, 120, 121, 122, 123, 239, 240, 241, 242, 243, 359, 360, 361, 362, 363, 479, 480, 1, 2, 3.

Signals shown:

- /DSPOF
- FR
- LP
- VH
- VM
- VL
- O1
- O2
- O120
- O1
- O2
- O1
- O2
- O1
- O2
- DIO1 (IN)
- DIO2 (OUT)
- DIO1 (IN)
- DIO2 (OUT)
- DIO1 (IN)
- DIO2 (OUT)
- DIO1 (IN)
- DIO2 (OUT)

Timing Diagram 2 (Blanking function)



Absolute Maximum Ratings

(Ensure that the following conditions are maintained, $V_{CC} \geq V_H \geq V_{DD} \geq V_M \geq V_{SS} \geq V_L \geq V_{EE}$)
(Note 1)

Item	Symbol	Pin Name	Rating	Unit
Supply Voltage 1	V_{DD}	V_{DD}	-0.3 to 7.0	V
Supply Voltage 2	$V_{DD} - V_{EE}$	$V_{CC}/R, V_{EE}/R$	-0.3 to 85	V
	$V_H - V_{EE}$	$V_{HL}/R, V_{EEL}/R$	-0.3 to 85	
Supply Voltage 3	$V_M - V_{EE}$	$V_{ML}/R, V_{EEL}/R$	-0.3 to 85	V
Supply Voltage 4	$V_L - V_{EE}$	$V_{LL}/R, V_{EEL}/R$	-0.3 to 85	V
Input Voltage	V_{IN}	(Note 2)	-0.3 to $V_{DD} + 0.3$	V
Operating Temperature	T_{opr}	—	-20 to 75	°C
Storage Temperature	T_{stg}	—	-40 to 125	°C

Note 1: Input voltage: $V_{SS} \rightarrow V_{DD} \rightarrow V_{EE}/V_L \rightarrow V_{CC}/V_H \rightarrow V_M$

Note 2: LP, FR, DIR, DUAL, DIO1, DIO2, DMIN, /DSPOF, /BLNK, TEST

Electrical Characteristics**DC Characteristics**

(Unless Otherwise Noted, $V_{SS} = 0\text{ V}$, $V_{DD} = 2.7\text{ to }5.5\text{ V}$, $T_a = -20\text{ to }75^\circ\text{C}$)

(Ensure that the following conditions are maintained, $V_{CC} \geq V_H \geq V_{DD} \geq V_M \geq V_{SS} \geq V_L \geq V_{EE}$)

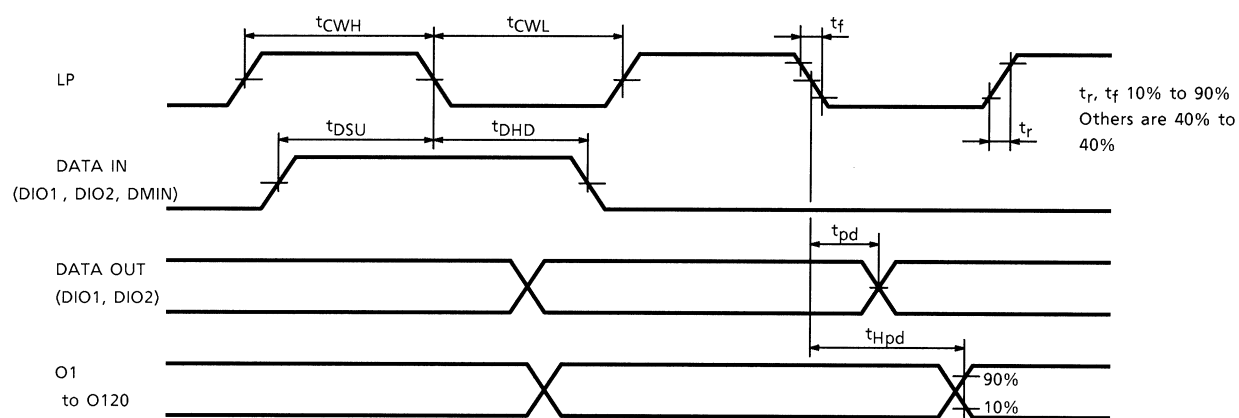
Item		Symbol	Test Circuit	Test Condition		Min	Typ.	Max	Unit	Pin Name	
Supply Voltage 1		V _{DD}	—	—		2.7	5.0	5.5	V	V _{DD}	
Supply Voltage 2		$V_{CC} - V_M$ $V_M - V_{EE}$	—	—		16	—	40	V	V_{CCL} / R V_{EEL} / R	
Input Voltage	H Level	V _{IH}	—	(Note 3)		0.6 V _{DD}	—	V _{DD}	V	(Note 2)	
	L Level	V _{IL}	—	(Note 3)		0	—	0.2 V _{DD}			
Output Voltage	H Level	V _{OH}	—	I _{OH} = -0.5 mA		V _{DD} - 0.5	—	V _{DD}	V	DIO1 DIO2	
	L Level	V _{OL}	—	I _{OL} = 0.5 mA		0	—	0.5			
Output Resistance	H Level	R _{OH}	—	V _{OUT} = V _H - 0.5 V (Note 4)		—	0.6	1.2	kΩ	O1 to O120	
	M Level	R _{OM}	—	V _{OUT} = V _M + 0.5 V (Note 4)		—	0.6	1.2			
		R _{OM}	—	V _{OUT} = V _M - 0.5 V (Note 4)		—	0.6	1.2			
	L Level	R _{OL}	—	V _{OUT} = V _L + 0.5 V (Note 4)		—	0.6	1.2			
Current Consumption		I _{DD} Ope	—	V _{DD} = 5.5 V	V _{CC} - V _{EE} = 80 V	Function (Note 5)	—	—	60	μA	V _{DD}
				V _{DD} = 2.7 V			—	—	30		
		I _{CC} Ope		V _{DD} = 5.5 V		Function (Note 5)	—	—	200		V _{CC} L / R
				V _{DD} = 2.7 V			—	—	200		
		I _{CC} Leak		V _{DD} = 5.5 V		Standby	-10	—	10		V _{CC} L / R

Note 3: $V_{DD} = 4.5\text{ to }5.5\text{ V}$, $V_{DD} = 2.7\text{ V}$: $V_{IH} = 0.7 V_{DD}$ (min), $V_{IL} = 0.2 V_{DD}$ (max)

Note 4: $V_{DD} = 2.7\text{ V}$, $V_H = 32.5\text{ V}$, $V_M = 2.5\text{ V}$, $V_L = -27.5\text{ V}$

Note 5: No load, $f_{LP} = 48\text{ kHz}$, $f_{FR} = 2.4\text{ kHz}$, $f_{DIO} = 400\text{ Hz}$, $V_{IH} = V_{DD}$, $V_{IL} = V_{SS}$

AC Characteristics



Test Conditions (1) ($V_{DD} = 4.5$ to 5.5 V)

Item	Symbol	Test Condition	Min	Max	Unit
LP Pulse Width H	t_{CWH}	LP	30	—	ns
LP Pulse Width L	t_{CWL}	LP	195	—	ns
Input Rise / Fall Time	t_r, t_f	LP, FR, DIO1, DIO2, DMIN	—	50	ns
Data Set-up Time	t_{DSU}	DIO1, DIO2, DMIN	30	—	ns
Data Hold Time	t_{DHD}	DIO1, DIO2, DMIN	30	—	ns
Output Data Delay Time (Note 6)	t_{pd}	DIO1, DIO2, DMIN	40	150	ns
LCD Drive Data Delay Time (Note 7)	t_{Hpd}	O1 to O120	—	1.0	μ s

Note 6: $C_L = 30$ pF

Note 7: No load, $V_{SS} = 0$ V, $V_M = 2.5$ V, $V_H = 42.5$ V, $V_L = -37.5$ V

Test Conditions (2) ($V_{DD} = 2.7$ to 4.5 V)

Item	Symbol	Test Condition	Min	Max	Unit
LP Pulse Width H	t_{CWH}	LP	100	—	ns
LP Pulse Width L	t_{CWL}	LP	400	—	ns
Input Rise / Fall Time	t_r, t_f	LP, FR, DIO1, DIO2, DMIN	—	50	ns
Data Set-up Time	t_{DSU}	DIO1, DIO2, DMIN	60	—	ns
Data Hold Time	t_{DHD}	DIO1, DIO2, DMIN	30	—	ns
Output Data Delay Time (Note 8)	t_{pd}	DIO1, DIO2, DMIN	40	400	ns
LCD Drive Data Delay Time (Note 9)	$t_{Hp d}$	O1 to O120	—	1.2	μ s

Note 8: $C_L = 30$ pF

Note 9: No load, $V_{SS} = 0$ V, $V_M = 2.5$ V, $V_H = 42.5$ V, $V_L = -37.5$ V

Note: Insert the bypass capacitor (0.1 μ F) between V_{DD} and V_{SS} to decrease power supply noise.

Position the bypass capacitor as close to the LSI as possible.

Set/DSPDF to L at power on so as to protect power supply IC.

Pay attention to measure and treatment of latch-up because being high-withstand pressure product.

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